Abstract

In order to achieve an integration of functional structures into the housing of electronic components, provision is made of a method for producing an electronic component comprising at least one semiconductor element having at least one sensor-technologically active and/or emitting device on at least one side, the method comprising the following steps:

- provision of at least one die on a wafer,
- production of at least one patterned support having at least one structure which is functional for the sensor-technologically active and/or emitting device,
- joining together of the wafer with the at least one support, so that that side of the die which has the sensor-technologically active and/or emitting device faces the support,
- separation of the die.

Figure 1A

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